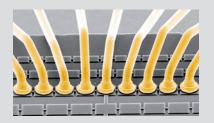
## Heraeus

## Au HA3

## Low Loop • High Reliability • Bumping



In contrast to doped Au wires, alloyed wire types contain a low percentage of alloying elements. This results in markedly higher wire strength, shorter heat affected zones and better thermal stability without a significant increase in electrical resistance. The increased wire strength, while maintaining all other mechanical properties, permits a reduction of



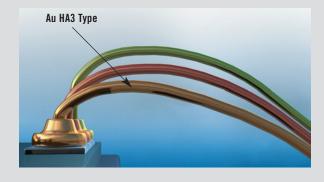
wire diameter together with a marked saving in precious metal costs.

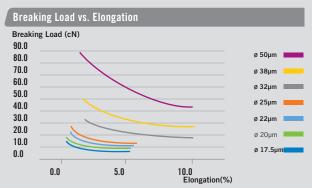
Areas of application

- High frequency bonding
- Low temperature bonding
- Low- and long-loop bonding
- High speed bonding
- Ultra fine pitch bonding
- Ball bumping

## Au HA3 Benefits

- High reliability wire type
- Increased strength, high loop stiffness
- Very good pull strengths and shear
- Long & low loop geometries
- Optimum stabilized phase formation
- High thermal stability

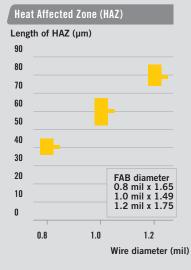


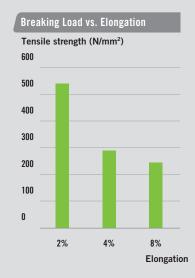


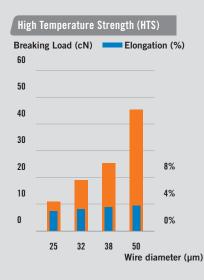
Recommended Technical Data of Au HA3										
Diameter	Microns (µm)	17.5	20	23	25	30	33	38	50	
	Mils	0.7	8.0	0.9	1.0	1.2	1.3	1.5	2.0	
Elongation	%	2 - 6	2 - 6	2 - 6	2 - 8	2 - 8	3 - 8	3 - 8	3 - 8	
Breaking Load	cN	> 5	> 6	> 8	> 10	> 15	> 18	> 22	> 40	

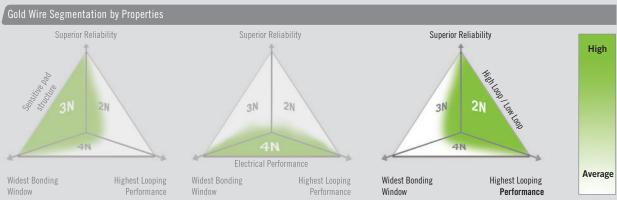
For other diameters, please contact Heraeus Bonding wires sales representative.

Heat Conductivity	3.03 W/cm.K			
Electrical Resistivity	2.9μΩ-cm			
Coeff. of Linear Expansion (20 $-$ 100 $^{\circ}\text{C})$	14.2 ppm / K			
Fusing Current for 25 µm, dia 10 mm length (in air)	0.35 A			









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The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can be supplied upon request). Although the data is considered accuract, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for particular application.